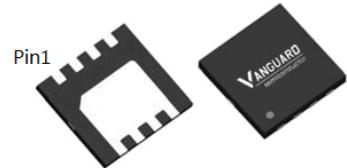


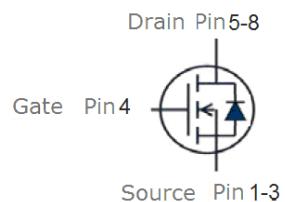
## Features

- N-Channel, 5V Logic Level Control
- Enhancement mode
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5V$
- Fast Switching
- Pb-free lead plating; RoHS compliant

$V_{DS}$	40	V
$R_{DS(on),TYP} @ V_{GS}=10V$	7.2	$m\Omega$
$R_{DS(on),TYP} @ V_{GS}=4.5V$	11	$m\Omega$
$I_D$	53	A

**TDFN3.3x3.3**


Part ID	Package Type	Marking	Tape and reel information
VS4610AB	TDFN3.3x3.3	4610AB	5000pcs/Reel



## Maximum ratings, at $T_j=25^{\circ}\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	40	V
$I_s$	Diode continuous forward current	$T_c=25^{\circ}\text{C}$	A
$I_D$	Continuous drain current@ $V_{GS}=10V$	$T_c=25^{\circ}\text{C}$	A
		$T_c=100^{\circ}\text{C}$	A
$I_{DM}$	Pulse drain current tested ①	$T_c=25^{\circ}\text{C}$	A
EAS	Avalanche energy, single pulsed ②	40	mJ
$P_d$	Maximum power dissipation	$T_c=25^{\circ}\text{C}$	W
$V_{GS}$	Gate-Source voltage	$\pm 20$	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 150	$^{\circ}\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.8	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	35	$^{\circ}\text{C}/\text{W}$



## Typical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	40	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>c</sub> =25 °C)	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>c</sub> =125 °C)	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.3	1.7	2.4	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =15A	--	7.2	9.5	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	--	11	14	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1MHz	1700	2015	2300	pF
C <sub>oss</sub>	Output Capacitance		120	170	220	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		60	110	160	pF
R <sub>g</sub>	Gate Resistance		--	2.1	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =20V, I <sub>D</sub> =15A, V <sub>GS</sub> =10V	--	49.6	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	8	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	16.4	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =20V, I <sub>D</sub> =15A, R <sub>G</sub> =3Ω, V <sub>GS</sub> =10V	--	9.4	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	7.1	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	30.2	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	7.5	--	nS
<b>Source- Drain Diode Characteristics@ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =15A, V <sub>GS</sub> =0V	--	0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>j</sub> =25 °C, I <sub>SD</sub> =15A, V <sub>GS</sub> =0V di/dt=100A/μs	--	36	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge		--	48	--	nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T<sub>jmax</sub>, starting T<sub>j</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 10A, V<sub>GS</sub> = 10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycles≤ 2%.



Vanguard  
Semiconductor

VS4610AB

40V/53A N-Channel Advanced Power MOSFET

## Typical Characteristics

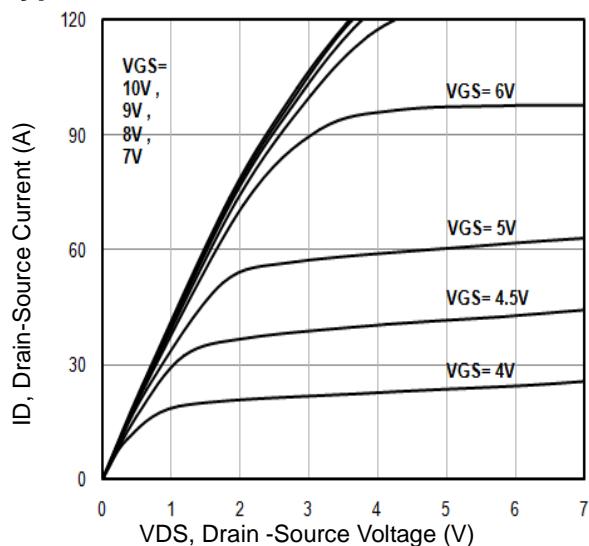


Fig1. Typical Output Characteristics

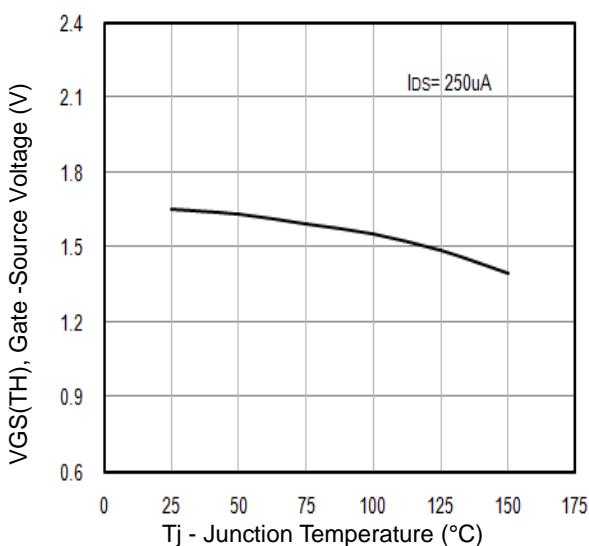


Fig2.  $V_{GS(TH)}$  Gate -Source Voltage Vs. $T_j$

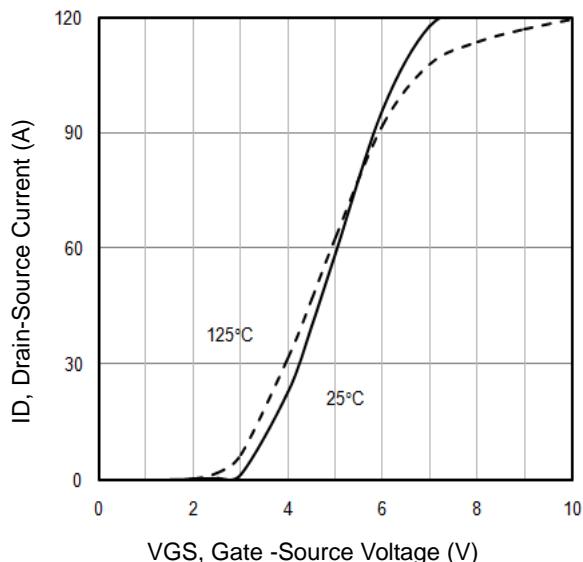


Fig3. Typical Transfer Characteristics

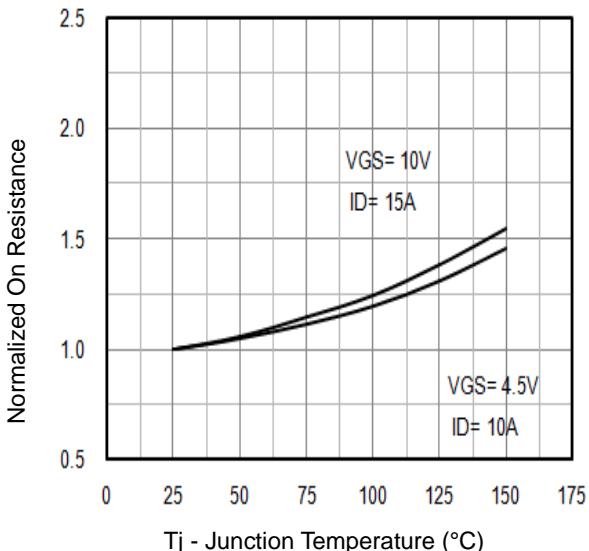


Fig4. Normalized On-Resistance Vs.  $T_j$

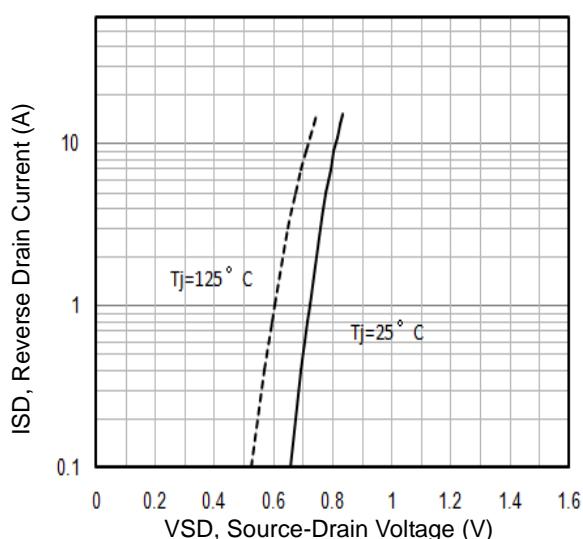


Fig5. Typical Source-Drain Diode Forward Voltage

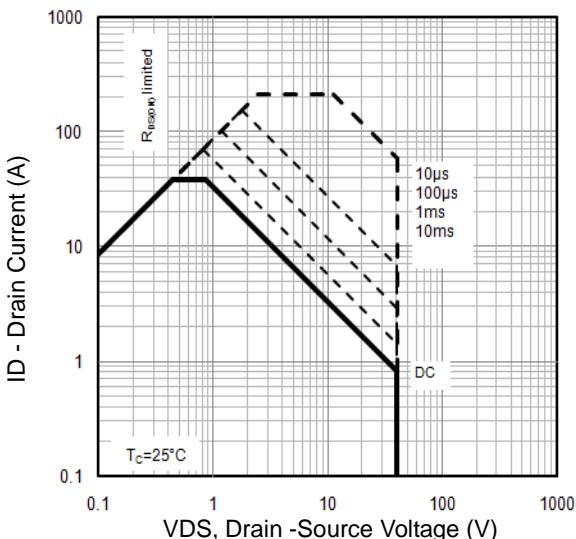


Fig6. Maximum Safe Operating Area



## Typical Characteristics

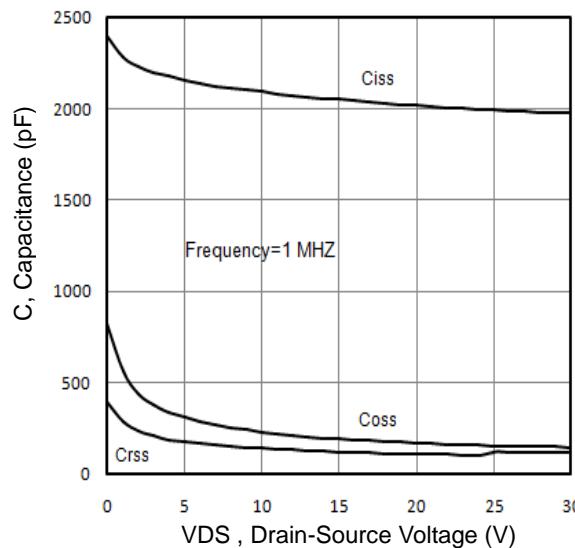


Fig7. Typical Capacitance Vs.Drain-Source Voltage

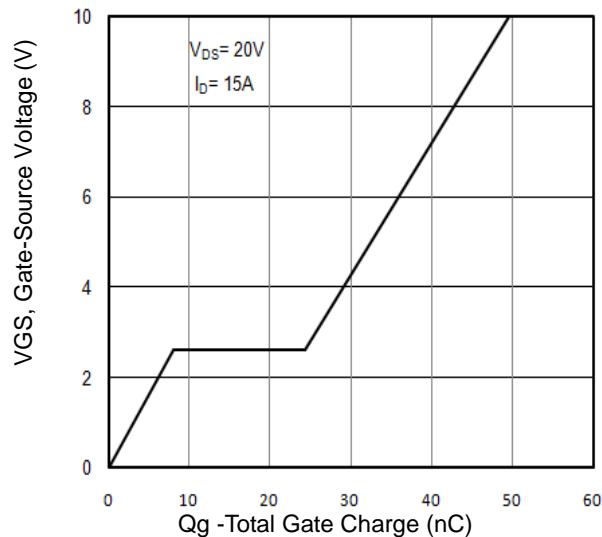


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

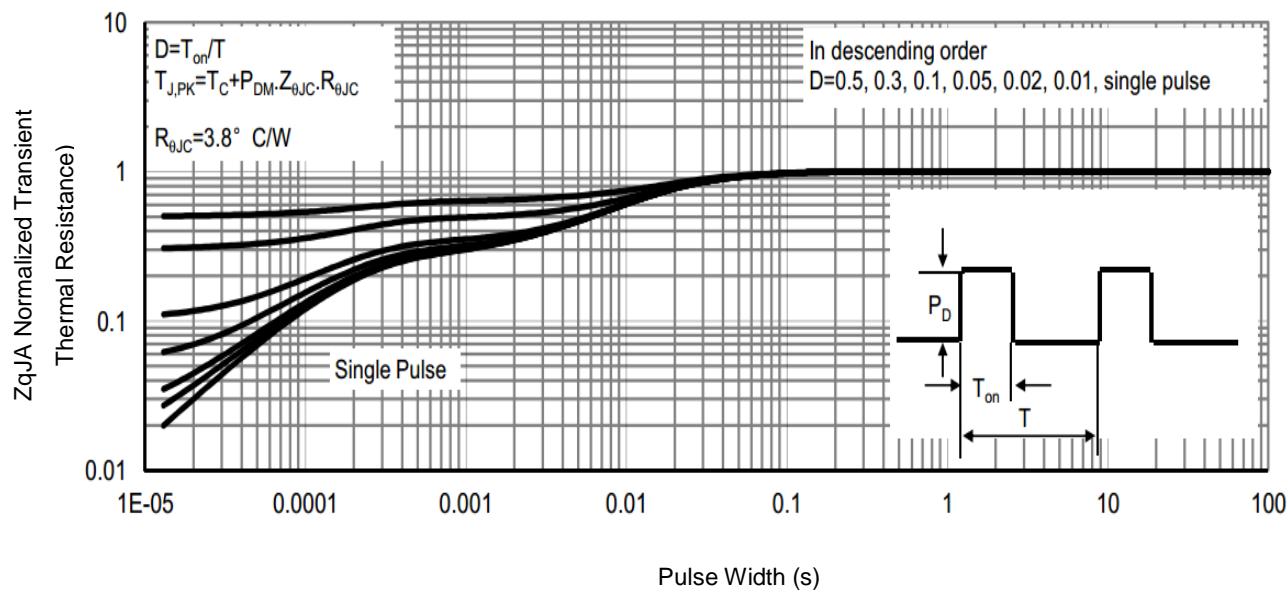


Fig9. Normalized Maximum Transient Thermal Impedance

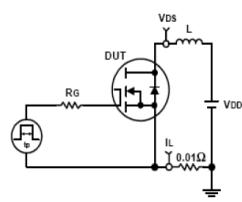


Fig10. Unclamped Inductive Test Circuit and waveforms

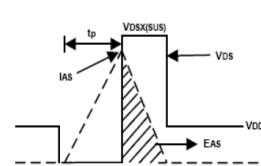
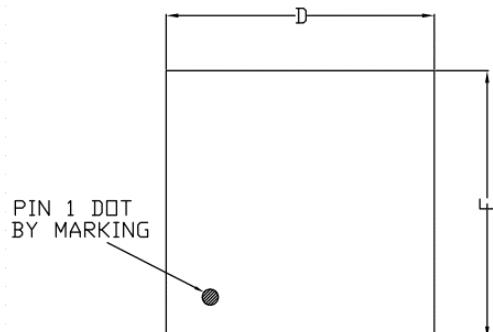


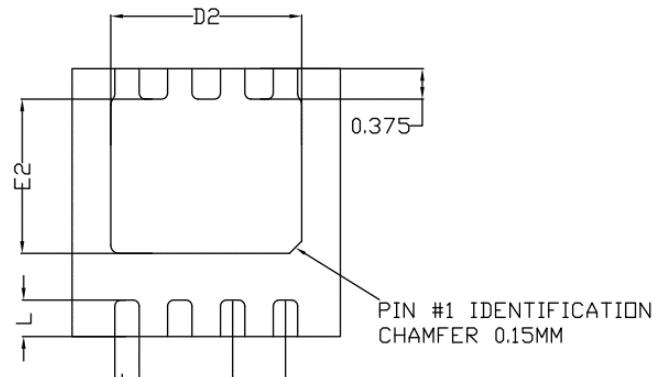
Fig11. Switching Time Test Circuit and waveforms



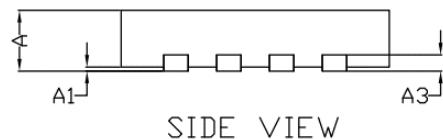
### TDFN3.3x3.3 Package Outline Data



TOP VIEW



BOTTOM VIEW



SIDE VIEW

Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	0.70	0.75	0.80
A1	0.00	--	0.05
A3	0.20 REF		
D	3.25	3.30	3.35
E	3.25	3.30	3.35
D2	2.30	2.35	2.40
E2	1.85	1.90	1.95
b	0.25	0.30	0.35
L	0.35	0.45	0.55
e	0.65 BSC		

#### Notes:

1. Refer to JEDEC MO-240 variation CA.

## Customer Service

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